

Applicant/Grantee		Microchip Technology Inc.		
FCC ID:		2ADHKWFI32E01		
Section 15.212 Modular Transmitters /				
X	Request for Modular Approval		Request for Limited Modular Approval	
	Requirements		Device Conditions	
Comply (Y/N)				
Single Modular Approval Requirements				
1	The radio elements must have the radio frequency circuitry must be shielded. Physical/discrete and tuning capacitors may be located external to the shield, but must be on the module assembly.		The module has its own RF shielding. Shield Can is employed on the board structure, please see exhibition External Photo, the emission measurement was conducted without further shielding added.	
2	The module shall have buffered modulation/data input(s) (if such inputs are provided) to ensure that the module will comply with the requirements set out in the applicable RSS standard under conditions of excessive data rates or over-modulation.		All modulation and data input(s) are Buffered on the EUT. These are integrated on the RF chip	
3	The module shall have its own power supply regulation on the module. This is to ensure that the module will comply with the requirements set out in the applicable standard regardless of the design of the power supplying circuitry in the host device which houses the module. Requirements set out in the applicable standard regardless of the design of the power supplying circuitry in the host device which houses the module.		RF System on Chip IC contains multiple dedicated voltage regulators for transmitter chain including modulator, pre-power amplifier. Output power is controlled by the RF Chip and de-coupled from supply voltage variations.	
4	The module shall comply with the provisions for external power amplifiers and antennas detailed in this standard. The Equipment certification submission shall contain a detailed description of the configuration of all antennas that will be used with the module.		Module Variants have below antenna approaches: #1 The Antenna is part of the module #2 Include different antenna assy. in the list, it is connected by an u.FL connector based cable to EUT.	
5	The module shall be tested for compliance with the applicable standard in a stand-alone configuration, i.e. the module must not be inside another device during testing.		The modular transmitter was tested in a stand-alone configuration. See Setup Photos.	
6	The module shall comply with the Category I equipment labelling requirements.		In the exhibition OEM manual, there are Instructions given to the OEM on how to label the end product. See Label Exhibit.	

7	The modular transmitter complies with all specific rules or operating requirements that ordinarily apply to a complete transmitter and the manufacturer will provide adequate instructions along with the module to explain any such requirements. A copy of these instructions is included in this application for equipment authorization:	Instructions in User Manual	Y
8a	Address compliance with the Commission's RF exposure limits in Sections 1.1310 and 2.1093. In addition, spread spectrum transmitters operating under Section 15.247 are required to address RF exposure compliance in accordance with Section 15.247(b)(4).	Please refer the Maximum Permissible Exposure Information.	Y

A **limited modular approval** may be granted for single or split modular transmitters that do not comply with all of the above requirements, *e.g.*, shielding, minimum signaling amplitude, buffered modulation/data inputs, or power supply regulation, if the manufacturer can demonstrate by alternative means in the application for equipment authorization that the modular transmitter meets all the applicable Part 15 requirements under the operating conditions in which the transmitter will be used. Limited modular approval also may be granted in those instances where compliance with RF exposure rules is demonstrated only for particular product configurations. The applicant for certification must state how control of the end product into which the module will be installed will be maintained such that full compliance of the end product is always ensured.

Signature 
Name/Title: Steve Caldwell / Vice President
Company Name: Microchip Technology Inc.
Date: June 30, 2021